

## DATA SHEET

Order code	Manufacturer code	Description		
38-1038	GPVO-0.060-00-0404	GAP PAD VO 0.060" 4" X 4" SHEET RC		
38-1040	GPVO-0.125-00-0404	GAP PAD VO 0.125" 4" X 4" SHEET RC		

	Page 1 of 2
The enclosed information is believed to be correct, Information may change without noticeque to	Revision A
product improvement. Users should ensure that the product is suitable for their use. E. & O. E.	20/02/2007

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# Gap Pad VO®

#### Conformable, Thermally Conductive Material for Filling Air Gaps

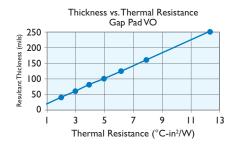
#### **Features and Benefits**

- Thermal conductivity: 0.8 W/m-K
- Enhanced puncture, shear and tear resistance
- Conformable gap filling material
- · Electrically isolating



Gap Pad VO is a cost-effective, thermally conductive interface material. The material is a filled, thermally conductive polymer supplied on a rubber-coated fiberglass carrier allowing for easy material handling. The conformable nature of Gap Pad VO allows the pad to fill in air gaps between PC boards and heat sinks or a metal chassis.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PRO	<b>OPERTIES OF</b>	<b>GAP PAD VO</b>			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD		
Color	Gold/Pink	Gold/Pink	Visual		
Reinforcement Carrier	Sil-Pad	Sil-Pad	_		
Thickness (inch) / (mm)	0.020 to 0.250	0.508 to 6.350	ASTM D374		
Inherent Surface Tack (I- or 2-sided)	I		_		
Density (g/cc)	1.6	1.6	ASTM D792		
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269		
Hardness, Bulk Rubber (Shore 00) (1)	40	40	ASTM D2240		
Young's Modulus (psi) / (kPa) (2)	100	689	ASTM D575		
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	_		
ELECTRICAL					
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149		
Dielectric Constant (1000 Hz)	5.5	5.5	ASTM D150		
Volume Resistivity (Ohm-meter)	1011	1011	ASTM D257		
Flame Rating	V-O	V-O	U.L. 94		
THERMAL					
Thermal Conductivity (W/m-K)	0.8	0.8	ASTM D5470		
1) Thirty second delay value Shore 00 hardness scale.					

<sup>2)</sup> Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116

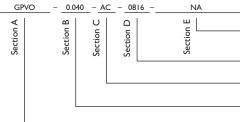
#### **Typical Applications Include:**

- Telecommunications
- Computer and peripherals
- Power conversion
- Between heat-generating semiconductors and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader
- Between heat-generating magnetic components and a heat sink

### **Configurations Available:**

• Sheet form and die-cut parts

### **Building a Part Number**



#### **Standard Options**

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and

0816 = Standard sheet size 8" x 16" or 00 = custom configuration

AC = Adhesive, one side 00 = No pressure sensitive adhesive

Standard thicknesses available: 0.020", 0.040", 0.060",

0.080", 0.100", 0.125", 0.160", 0.200", 0.250'

revision level.

Note: To build a part number, visit our website at www.bergquistcompany.com. Gap Pad®: U.S. Patent 5,679,457 and others.